

ADC1175-50

ADC1175-50 8-Bit, 50 MSPS, 125 mW A/D Converter



Literature Number: SNAS027F

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8-Bit, 50 MSPS, 125 mW A/D Converter

General Description

The ADC1175-50 is a low power, 50 MSPS analog-to-digital converter that digitizes signals to 8 bits while consuming just 125 mW (typ). The ADC1175-50 uses a unique architecture that achieves 6.8 Effective Bits at 25 MHz input and 50 MHz clock frequency. Output formatting is straight binary coding.

The excellent DC and AC characteristics of this device, together with its low power consumption and +5V single supply operation, make it ideally suited for many video and imaging applications, including use in portable equipment. Furthermore, the ADC1175-50 is resistant to latch-up and the outputs are short-circuit proof. The top and bottom of the ADC1175-50's reference ladder is available for connections, enabling a wide range of input possibilities. The low input capacitance (7 pF, typical) makes this device easier to drive than conventional flash converters and the power down mode reduces power consumption to less than 5 mW.

The ADC1175-50 is offered in TSSOP and is designed to operate over the extended commercial temperature range of -20°C to $+75^{\circ}\text{C}$.

Features

- Internal Track-and-Hold function
- Single +5V operation
- Internal reference bias resistors
- Industry standard pinout
- Power-down mode (<5 mW)

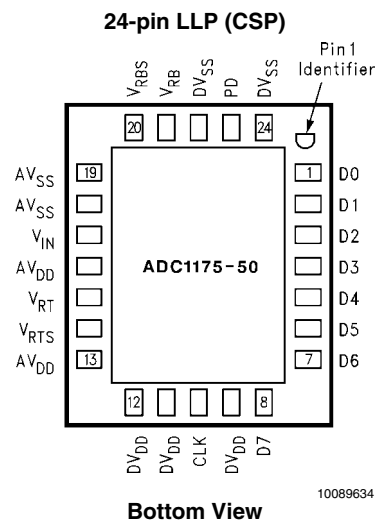
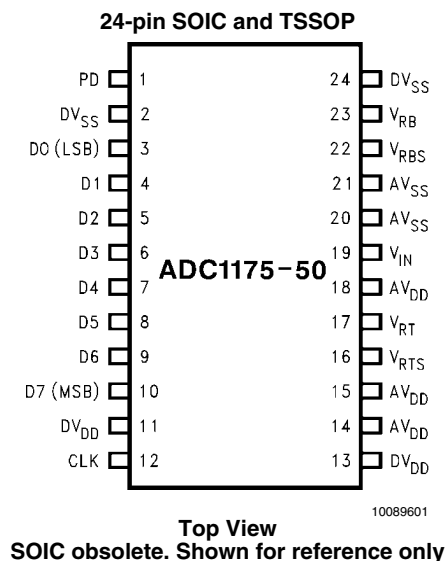
Key Specifications

- | | |
|---|----------------------------|
| ■ Resolution | 8 Bits |
| ■ Maximum Sampling Frequency | 50 MSPS (min) |
| ■ THD | 54 dB (typ) |
| ■ DNL | 0.7 LSB (typ) |
| ■ ENOB @ $f_{IN} = 25\text{ MHz}$ | 6.8 Bits (typ) |
| ■ Guaranteed No Missing Codes | |
| ■ Power Consumption (Excluding Reference Current) | 125 mW (typ), 190 mW (max) |

Applications

- Digital Still Cameras
- CCD Imaging
- Electro-Optics
- Video Digitization
- Multimedia

Connection Diagrams

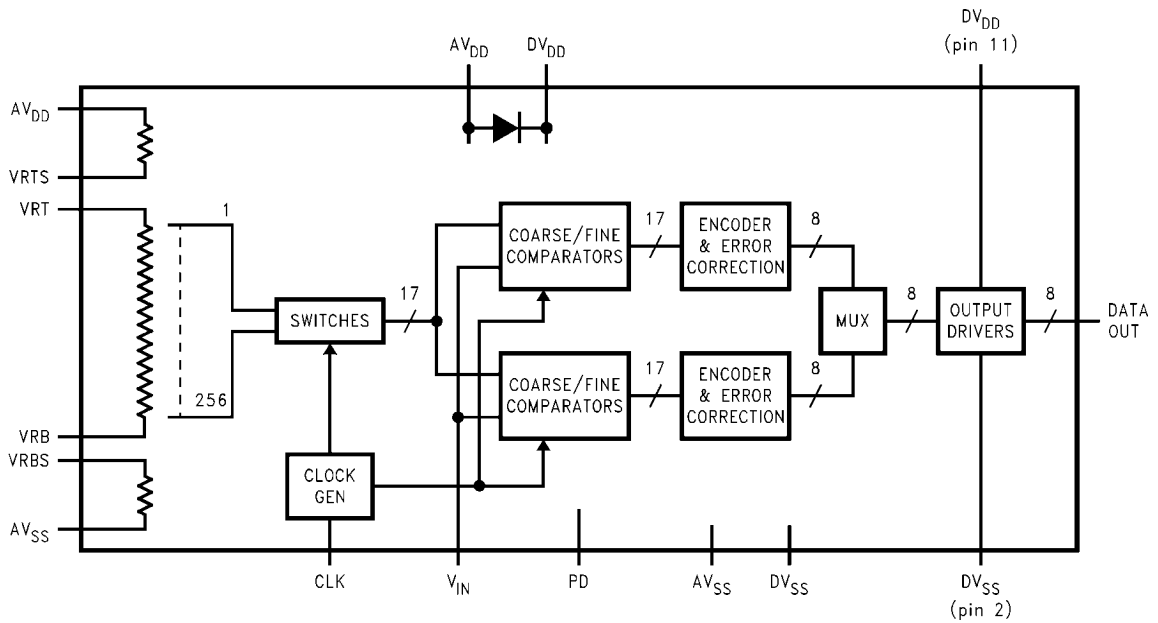


Ordering Information

| Order Code | Temperature Range | Description |
|-------------------|-------------------|---------------------------------|
| ADC1175-50CIJM * | -20°C to +70°C | SOIC (EIAJ) |
| ADC1175-50CIJMX * | -20°C to +70°C | SOIC (EIAJ) tape and reel |
| ADC1175-50CIMT | -20°C to +70°C | TSSOP |
| ADC1175-50CIMTX | -20°C to +70°C | TSSOP (tape and reel) |
| ADC1175-50CILQ * | -20°C to +70°C | LLP tape and reel (1,000 units) |
| ADC1175-50CILQX * | -20°C to +70°C | LLP tape and reel (4,500 units) |
| ADC1175-50EVAL * | | Evaluation Board |

Obsolete in the SOIC (EIAJ) and LLP packages. The Evaluation Board is also discontinued. Shown for reference only.

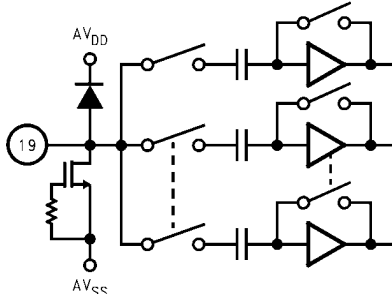
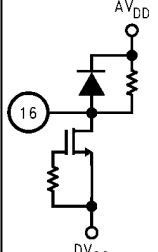
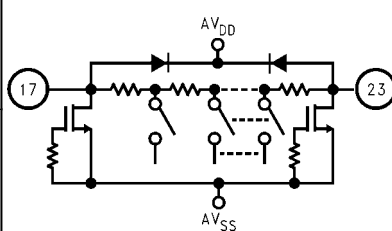
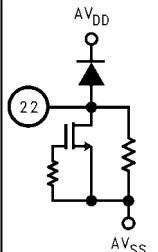
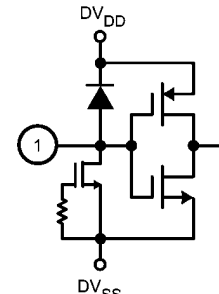
Block Diagram



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Pin Descriptions and Equivalent Circuits

(LLP pins in parentheses)

| Pin No. | Symbol | Equivalent Circuit | Description |
|------------|-----------|---|--|
| 19 (17) | V_{IN} |  | Analog signal input. Conversion range is V_{RT} to V_{RB} . |
| 16 (14) | V_{RTS} |  | Reference Top Bias with internal pull up resistor. Short this pin to V_{RT} to self-bias the reference ladder. |
| 17 (15) | V_{RT} |  | Analog input that is the high (top) side of the reference ladder of the ADC. Voltages on V_{RT} and V_{RB} inputs define the V_{IN} conversion range. Bypass well. See Section 2.0 for more information. |
| 23 (21) | V_{RB} | | Analog input that is the low (bottom) side of the reference ladder of the ADC. Nominal range is 0.0V to 4.0V, with optimized value of 0.6V. Voltage on V_{RT} and V_{RB} inputs define the V_{IN} conversion range. Bypass well. See Section 2.0 for more information. |
| 22 (20) | V_{RBS} |  | Reference Bottom Bias with internal pull down resistor. Short to V_{RB} to self-bias the reference ladder. Bypass well (unless grounded). See Section 2.0 for more information. |
| 1 (23) | PD |  | CMOS/TTL compatible Digital input that, when high, puts the ADC1175-50 into a power-down mode where total power consumption is typically less than 5 mW. With this pin low, the device is in the normal operating mode. |

| Pin No. | Symbol | Equivalent Circuit | Description |
|---------------------------------|------------------|--------------------|---|
| 12 (10) | CLK | | CMOS/TTL compatible digital clock input. V_{IN} is sampled on the falling edge of CLK input. |
| 3 thru 10 (1 thru 8) | D0-D7 | | Conversion data digital Output pins. D0 is the LSB, D7 is the MSB. Valid data is output just after the rising edge of the CLK input. These pins are in a high impedance mode when the PD pin is low. |
| 11, 13, 14 (9, 11, 12) | DV _{DD} | | Positive digital supply pin. Connect to a quiet voltage source of +5V. AV _{DD} and DV _{DD} should have a common source and be separately bypassed with a 10 μ F capacitor and a 0.1 μ F ceramic chip capacitor. See Section 4.0 for more information. |
| 2, 24 (22, 24) | DV _{SS} | | The ground return for the digital supply. AV _{SS} and DV _{SS} should be connected together close to the ADC1175-50. |
| 15, 18 (13, 16) | AV _{DD} | | Positive analog supply pin. Connect to a quiet voltage source of +5V. AV _{DD} and DV _{DD} should have a common source and be separately bypassed with a 10 μ F capacitor and a 0.1 μ F ceramic chip capacitor. See Section 4.0 for more information. |
| 20, 21 (18, 19) | AV _{SS} | | The ground return for the analog supply. AV _{SS} and DV _{SS} should be connected together close to the ADC1175-50 package. |

Absolute Maximum Ratings (Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

| | |
|---|-------------------------------------|
| Supply Voltage (AV _{DD} , DV _{DD}) | 6.5V |
| Voltage on Any Input or Output Pin | -0.3V to +6.5V |
| Reference Voltage (V _{RT} , V _{RB}) | AV _{SS} to V _{DD} |
| CLK, PD Voltage Range | -0.5 to (AV _{DD} + 0.5V) |
| Digital Output Voltage (V _{OH} , V _{OL}) | V _{SS} to V _{DD} |
| Input Current at Any Pin (Note 3) | ±25 mA |
| Package Input Current (Note 3) | ±50 mA |
| Power Dissipation at T _A = 25°C | See (Note 4) |
| ESD Susceptibility (Note 5) | |
| Human Body Model | 2000V |
| Machine Model | 250V |
| Soldering Temperature, Infrared, (10 sec.) (Note 6) | 235°C |
| Storage Temperature | -65°C to +150°C |
| Short Circuit Duration (Single High Output to Ground) | 1 Second |

Operating Ratings (Notes 1, 2)

| | |
|--|------------------------------------|
| Operating Temperature Range | -20°C ≤ T _A ≤ +75°C |
| Supply Voltage (AV _{DD} , DV _{DD}) | +4.75V to +5.25V |
| AV _{DD} - DV _{DD} | <0.5V |
| Ground Difference DV _{SS} - AV _{SS} | 0V to 100 mV |
| Pin 11 to Pin 13 Voltage | <0.5V |
| Upper Reference Voltage (V _{RT}) | 1.0V to V _{DD} |
| Lower Reference Voltage (V _{RB}) | 0V to 4.0V |
| V _{RT} - V _{RB} | 1V to 2.8V |
| V _{IN} Voltage Range | V _{RB} to V _{RT} |

Package Thermal Resistance

| Package | θ _{JA} |
|----------|-----------------|
| TSSOP-24 | 92°C / W |
| LLP-24 | 40°C / W |

Converter Electrical Characteristics

The following specifications apply for AV_{DD} = DV_{DD} = +5.0 V_{DC}, PD = 0V, V_{RT} = +2.6V, V_{RB} = 0.6V, C_L = 20 pF, f_{CLK} = 50 MHz at 50% duty cycle. **Boldface limits apply for T_A = T_{MIN} to T_{MAX}**; all other limits T_A = 25°C (Notes 7, 8).

| Symbol | Parameter | Conditions | Typical (Note 9) | Limits (Note 9) | Units (Limits) |
|--|-----------------------------------|---|------------------|---------------------------|----------------------|
| DC ACCURACY | | | | | |
| INL | Integral Non Linearity Error | V _{IN} = 0.6V to 2.6V | ±0.8 | ±1.95 | LSB (max) |
| DNL | Differential Non-Linearity | V _{IN} = 0.6V to 2.6V | +0.7 | +1.75 | LSB (max) |
| | | | -0.7 | -1.0 | LSB (min) |
| | Resolution for No Missing Codes | | | 8 | Bits |
| E _{OT} | Top Offset Voltage | | -12 | | mV |
| E _{OB} | Bottom Offset Voltage | | +10 | | mV |
| VIDEO ACCURACY | | | | | |
| DP | Differential Phase Error | f _{IN} = 4.43 MHz Modulated Ramp | 0.5 | | deg |
| DG | Differential Gain Error | f _{IN} = 4.43 MHz Modulated Ramp | 1.0 | | % |
| ANALOG INPUT AND REFERENCE CHARACTERISTIC | | | | | |
| V _{IN} | Input Range | | 2.0 | V _{RB} | V (min) |
| | | | | V _{RT} | V (max) |
| C _{IN} | V _{IN} Input Capacitance | V _{IN} = 1.5V +0.7 Vrms | (CLK LOW) | 4 | pF |
| | | | (CLK HIGH) | 7 | pF |
| R _{IN} | R _{IN} Input Resistance | | >1 | | MΩ |
| BW | Full Power Bandwidth | | 120 | | MHz |
| R _{RT} | Top Reference Resistor | | 320 | | Ω |
| R _{REF} | Reference Ladder Resistance | V _{RT} to V _{RB} | 270 | 200 350 | Ω (min) Ω (max) |
| R _{RB} | Bottom Reference Resistor | | 80 | | Ω |
| I _{REF} | Reference Ladder Current | V _{RT} = V _{RTS} , V _{RB} = V _{RBS} | 7 | 5.4 | mA (min) |
| | | | | 10.8 | mA (max) |
| | | V _{RT} = V _{RTS} , V _{RB} = AV _{SS} | 8 | 6.1 12.3 | mA (min) mA (max) |

| Symbol | Parameter | Conditions | Typical (Note 9) | Limits (Note 9) | Units (Limits) |
|--|------------------------------------|--|---------------------|----------------------------|---------------------|
| V_{RT} | Reference Top Self Bias Voltage | V_{RT} Connected to V_{RTS} , V_{RB} Connected to V_{RBS} | 2.6 | | V (min) V (max) |
| V_{RB} | Reference Bottom Self Bias Voltage | V_{RT} Connected to V_{RTS} , V_{RB} Connected to V_{RBS} | 0.6 | 0.55 0.70 | V (min) V (max) |
| $V_{RTS} - V_{RBS}$ | Self Bias Voltage Delta | V_{RT} Connected to V_{RTS} , V_{RB} Connected to V_{RBS} | 2 | 1.89 2.20 | (V (min) V (max) |
| | | V_{RT} Connected to V_{RTS} , V_{RB} Connected to AV_{SS} | 2.3 | | V |
| $V_{RT} - V_{RB}$ | Reference Voltage Differential | | 2 | 1.0 2.8 | V (min) V (max) |
| CONVERTER DYNAMIC CHARACTERISTICS | | | | | |
| ENOB | Effective Number of Bits | $f_{IN} = 4.4$ MHz, $f_{CLK} = 40$ MHz | 7.2 | 6.7 | Bits (min) |
| | | $f_{IN} = 19.9$ MHz, $f_{CLK} = 40$ MHz | 7.0 | 6.4 | Bits (min) |
| | | $f_{IN} = 1.3$ MHz, $f_{CLK} = 50$ MHz | 7.3 | | Bits |
| | | $f_{IN} = 4.4$ MHz, $f_{CLK} = 50$ MHz | 7.2 | | Bits |
| | | $f_{IN} = 24.9$ MHz, $f_{CLK} = 50$ MHz | 6.8 | 6.1 | Bits (min) |
| SINAD | Signal-to-Noise & Distortion | $f_{IN} = 4.4$ MHz, $f_{CLK} = 40$ MHz | 45 | 42 | dB (min) |
| | | $f_{IN} = 19.9$ MHz, $f_{CLK} = 40$ MHz | 44 | 40 | dB (min) |
| | | $f_{IN} = 1.3$ MHz, $f_{CLK} = 50$ MHz | 46 | | dB |
| | | $f_{IN} = 4.4$ MHz, $f_{CLK} = 50$ MHz | 45 | | dB |
| | | $f_{IN} = 24.9$ MHz, $f_{CLK} = 50$ MHz | 43 | 38.4 | dB (min) |
| SNR | Signal-to-Noise Ratio | $f_{IN} = 4.4$ MHz, $f_{CLK} = 40$ MHz | 46 | 42.5 | dB (min) |
| | | $f_{IN} = 19.9$ MHz, $f_{CLK} = 40$ MHz | 44 | 41 | dB (min) |
| | | $f_{IN} = 1.3$ MHz, $f_{CLK} = 50$ MHz | 48 | | dB |
| | | $f_{IN} = 4.4$ MHz, $f_{CLK} = 50$ MHz | 45 | | dB |
| | | $f_{IN} = 24.9$ MHz, $f_{CLK} = 50$ MHz | 44 | 40 | dB (min) |
| SFDR | Spurious Free Dynamic Range | $f_{IN} = 1.3$ MHz | 57 | | dB |
| | | $f_{IN} = 4.4$ MHz | 56 | | dB |
| | | $f_{IN} = 24.9$ MHz | 51 | | dB |
| THD | Total Harmonic Distortion | $f_{IN} = 1.3$ MHz | -55 | | dB |
| | | $f_{IN} = 4.4$ MHz | -54 | | dB |
| | | $f_{IN} = 24.9$ MHz | -51 | | dB |
| POWER SUPPLY CHARACTERISTICS | | | | | |
| $I_{A_{DD}}$ | Analog Supply Current | $DV_{DD} = AV_{DD} = 5.25V$ | 13 | | mA |
| $I_{D_{DD}}$ | Digital Supply Current | $DV_{DD} = AV_{DD} = 5.25V$ | 11 | | mA |
| $I_{A_{DD}} + I_{D_{DD}}$ | Total Operating Current | $DV_{DD} = AV_{DD} = 5.25V$, $f_{CLK} = 50$ MHz | 25 | 36 | mA (max) |
| | | $DV_{DD} = AV_{DD} = 5.25V$, CLK Inactive (low) | 14 | | mA |
| | Power Consumption | PD pin low | 125 | 190 | mW (max) |
| | Power Consumption | PD pin high | <5 mW | | mW |
| CLK, PD DIGITAL INPUT CHARACTERISTICS | | | | | |
| V_{IH} | Logical High Input Voltage | | | 2.0 | V (min) |
| V_{IL} | Logical Low Input Voltage | | | 0.8 | V (max) |
| I_{IH} | Logical High Input Current | $V_{IH} = DV_{DD} = AV_{DD} = +5.25V$ | | ±5 | μA (max) |
| I_{IL} | Logical Low Input Current | $V_{IL} = 0V$, $DV_{DD} = AV_{DD} = +5.25V$ | | ±5 | μA (max) |
| C_{IN} | Digital Input Capacitance | | 4 | | pF |
| DIGITAL OUTPUT CHARACTERISTICS | | | | | |
| I_{OH} | Output Current, Logic HIGH | $DV_{DD} = 4.75V$, $V_{OH} = 4.0V$ | | -1.1 | mA (min) |
| I_{OL} | Output Current, Logic LOW | $DV_{DD} = 4.75V$, $V_{OL} = 0.4V$ | | 1.8 | mA (min) |

| Symbol | Parameter | Conditions | Typical (Note 9) | Limits (Note 9) | Units (Limits) |
|--------------------|---------------------------|--|------------------|-----------------|----------------|
| I_{OZH}, I_{OZL} | TRI-STATE® Output Current | $DV_{DD} = 5.25V, PD = DV_{DD}, V_{OL} = DV_{DD}, \text{ or } V_{OL} = 0V$ | ± 20 | | μA |

AC ELECTRICAL CHARACTERISTICS

| | | | | | |
|----------|---------------------------|--------------------------------|-----|----|--------------|
| f_{C1} | Maximum Conversion Rate | | 55 | 50 | MHz (min) |
| f_{C2} | Minimum Conversion Rate | | 1 | | MHz |
| t_{OD} | Output Delay | CLK high to data valid | 14 | 5 | ns (min) |
| | | | | 20 | ns (max) |
| | Pipeline Delay (Latency) | | 2.5 | | Clock Cycles |
| t_{DS} | Sampling (Aperture) Delay | CLK low to acquisition of data | 3 | | ns |
| t_{AJ} | Aperture Jitter | | 10 | | ps rms |
| t_{OH} | Output Hold Time | CLK high to data invalid | 10 | | ns |
| t_{EN} | PD Low to Data Valid | Loaded as in <i>Figure 2</i> | 140 | | ns |

Note 1: "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Note 2: All voltages are measured with respect to $GND = AV_{SS} = DV_{SS} = 0V$, unless otherwise specified.

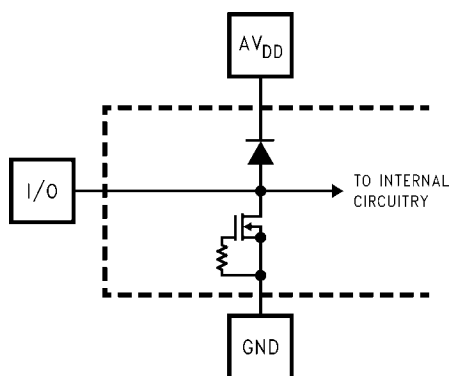
Note 3: When the input voltage at any pin exceeds the power supplies (that is, less than AV_{SS} or DV_{SS} , or greater than AV_{DD} or DV_{DD}), the current at that pin should be limited to 25 mA. The 50 mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 25 mA to two.

Note 4: The absolute maximum junction temperature ($T_J \text{ max}$) for this device is 150°C. The maximum allowable power dissipation is dictated by $T_J \text{ max}$, the junction-to-ambient thermal resistance (θ_{JA}) and the ambient temperature (T_A), and can be calculated using the formula $P_D \text{ max} = (T_J \text{ max} - T_A) / \theta_{JA}$. The values for maximum power dissipation listed above will be reached only when the ADC1175-50 is operated in a severe fault condition (e.g., when input or output pins are driven beyond the power supply voltages, or the power supply polarity is reversed). Obviously, such conditions should always be avoided.

Note 5: Human body model is 100 pF capacitor discharged through a 1.5 kΩ resistor. Machine model is 220 pF discharged through 0Ω.

Note 6: See AN-450, "Surface Mounting Methods and Their Effect on Product Reliability", or the section entitled "Surface Mount" found in any post 1986 National Semiconductor Linear Data Book for other methods of soldering surface mount devices.

Note 7: The analog inputs are protected as shown below. Input voltage magnitudes up to 6.5V or 500 mV below GND will not damage this device. However, errors in the A/D conversion can occur if the input goes above V_{DD} or below GND by more than 50 mV. As an example, if AV_{DD} is 4.75 V_{DC} , the full-scale input voltage must be $\leq 4.80 V_{DC}$ to ensure accurate conversions.

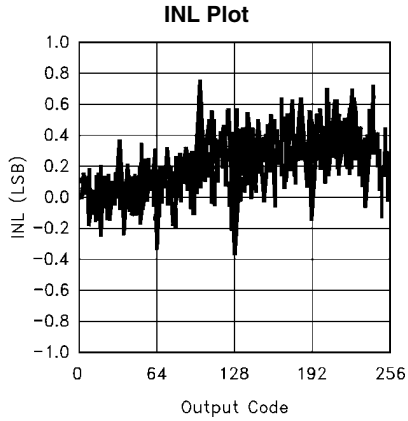


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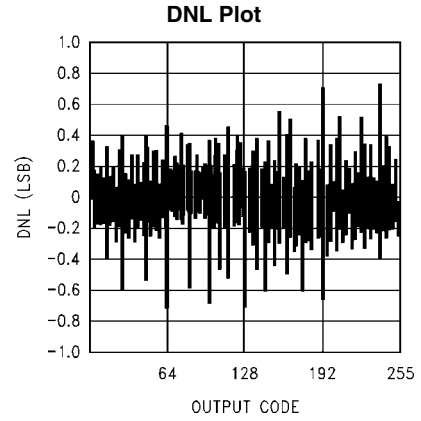
Note 8: To guarantee accuracy, it is required that AV_{DD} and DV_{DD} be well bypassed. Each V_{DD} pin must be decoupled with separate bypass capacitors.

Note 9: Typical figures are at $T_J = 25^\circ C$, and represent most likely parametric norms. Test limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

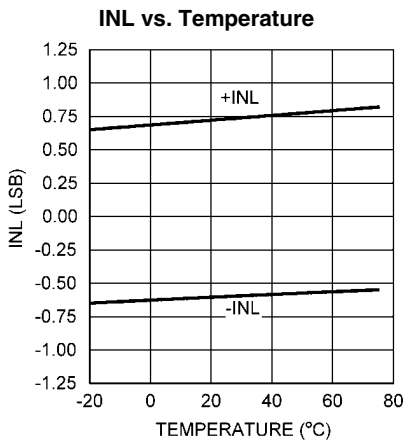
Typical Performance Characteristics $A_{V_{DD}} = D_{V_{DD}} = 5V$, $f_{CLK} = 50\text{ MHz}$, unless otherwise stated.



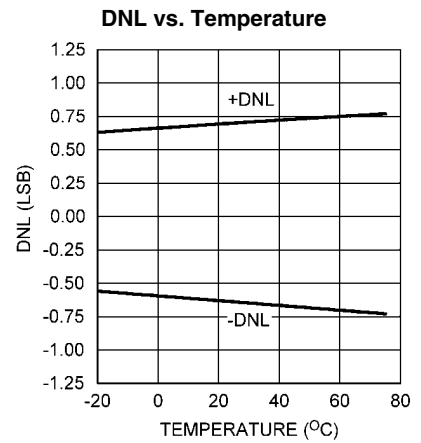
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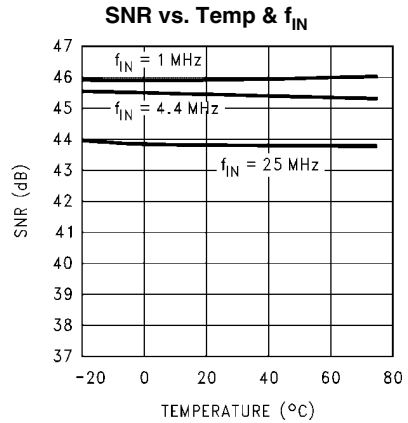
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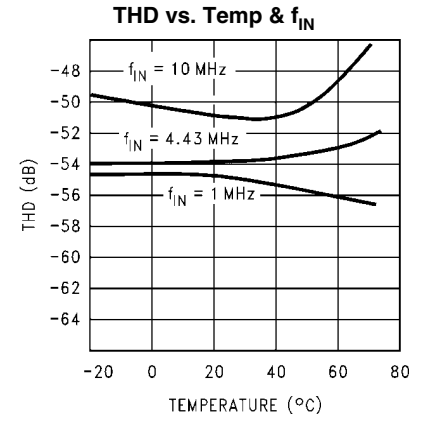
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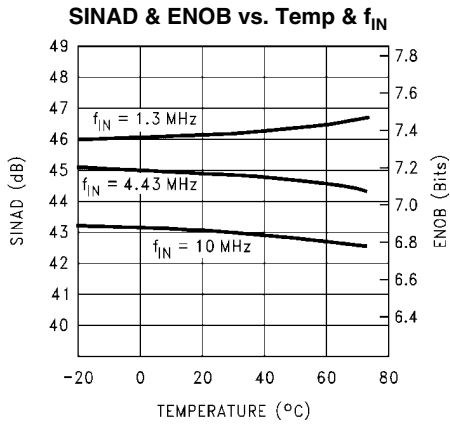
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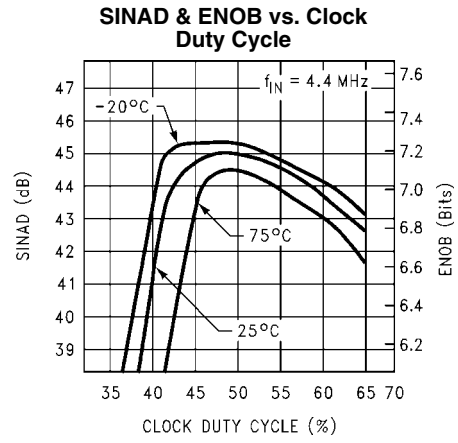
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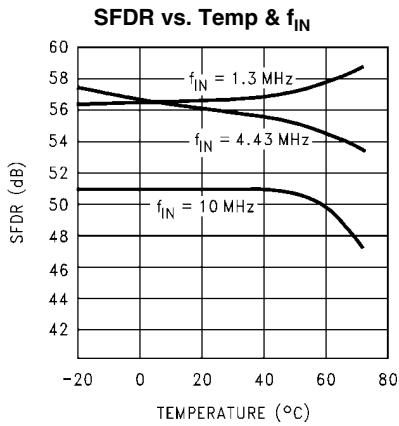
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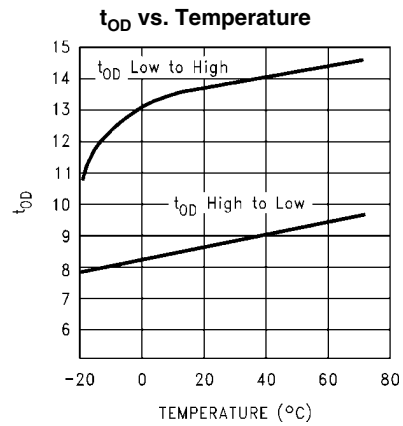
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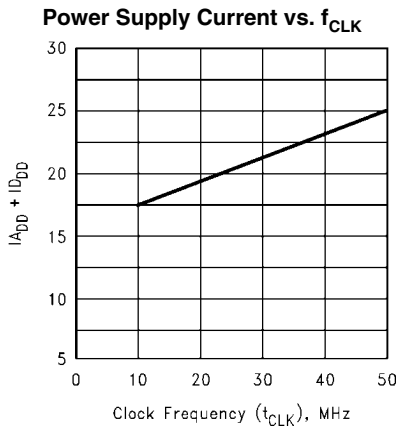
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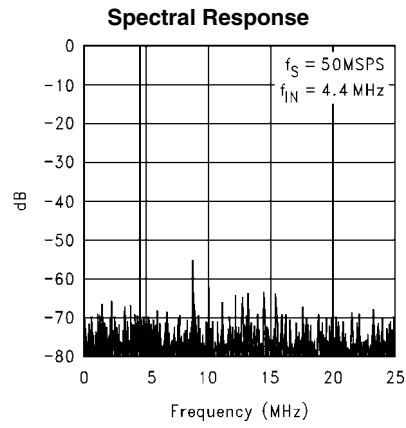
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10089621



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Specification Definitions

ANALOG INPUT BANDWIDTH is a measure of the frequency at which the reconstructed output fundamental drops 3 dB below its low frequency value for a full scale input. The test is performed with f_{IN} equal to 100 kHz plus integer multiples of f_{CLK} . The input frequency at which the output is -3 dB relative to the low frequency input signal is the full power bandwidth.

APERTURE JITTER is the time uncertainty of the sampling point (t_{DS}), or the range of variation in the sampling delay.

BOTTOM OFFSET is the difference between the input voltage that just causes the output code to transition to the first code and the negative reference voltage. Bottom Offset is defined as $E_{OB} = V_{ZT} - V_{RB}$, where V_{ZT} is the first code transition input voltage. Note that this is different from the normal Zero Scale Error.

DIFFERENTIAL GAIN ERROR is the percentage difference between the output amplitudes of a high frequency reconstructed sine wave at two different d.c. levels.

DIFFERENTIAL NON-LINEARITY (DNL) is the measure of the maximum deviation from the ideal step size of 1 LSB. DNL is measured at the rated clock frequency with a ramp input.

DIFFERENTIAL PHASE ERROR is the difference in the output phase of a reconstructed small signal sine wave at two different d.c. levels.

EFFECTIVE NUMBER OF BITS (ENOB, or EFFECTIVE BITS) is another method of specifying Signal-to-Noise and Distortion Ratio, or SINAD. ENOB is defined as $(SINAD - 1.76) / 6.02$ and says that the converter is equivalent to a perfect ADC of this (ENOB) number of bits.

INTEGRAL NON-LINEARITY (INL) is a measure of the deviation of each individual codes from a line drawn from zero scale (1/2 LSB below the first code transition) through positive full scale (1/2 LSB above the last code transition). The deviation of any given code from this straight line is measured from the center of that code value. The end point test method is used. INL is measured at rated clock frequency with a ramp input.

OUTPUT DELAY is the time delay after the rising edge of the input clock before the data update is present at the output pins.

OUTPUT HOLD TIME is the length of time that the output data is valid after the rise of the input clock.

PIPELINE DELAY (LATENCY) is the number of clock cycles between initiation of conversion and when that data is presented to the output stage. Data for any given sample is available the Pipeline Delay plus the Output Delay after that sample is taken. New data is available at every clock cycle, but the data lags the conversion by the pipeline delay.

SAMPLING (APERTURE) DELAY, or t_{DS} , is the time required after the falling edge of the clock for the sampling switch to open (in other words, for the Sample/Hold circuit to go from the "sample" mode into the "hold" mode). The Sample/Hold circuit effectively stops capturing the input signal and goes into the "hold" mode t_{DS} after the clock goes low.

SIGNAL TO NOISE RATIO (SNR) is the ratio of the rms value of the input signal to the rms value of the other spectral components below one-half the sampling frequency, not including harmonics or d.c.

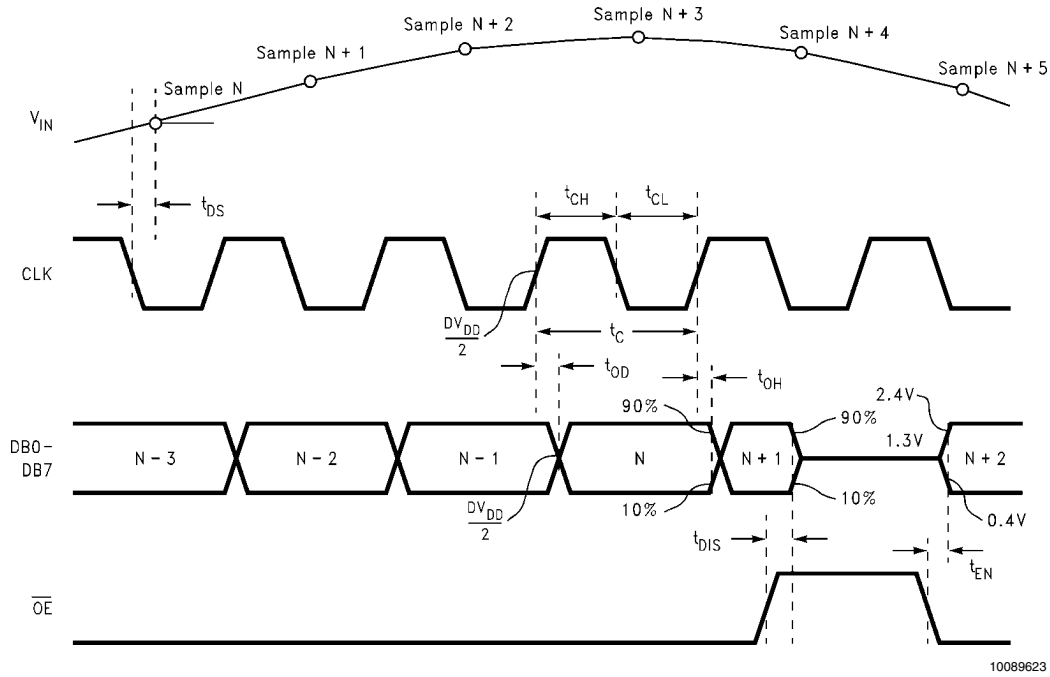
SIGNAL TO NOISE PLUS DISTORTION (S/(N+D) or SINAD) is the ratio of the rms value of the input signal to the rms value of all of the other spectral components below half the clock frequency, including harmonics but excluding d.c.

SPURIOUS FREE DYNAMIC RANGE (SFDR) is the difference, expressed in dB, between the rms values of the input signal and the peak spurious signal, where a spurious signal is any signal present in the output spectrum that is not present at the input.

TOP OFFSET is the difference between the positive reference voltage and the input voltage that just causes the output code to transition to full scale and is defined as $E_{OT} = V_{FT} - V_{RT}$. Where V_{FT} is the full scale transition input voltage. Note that this is different from the normal Full Scale Error.

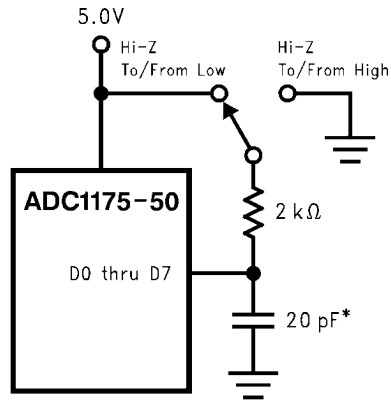
TOTAL HARMONIC DISTORTION (THD) is the ratio of the rms total of the first six harmonic components to the rms value of the input signal.

Timing Diagram



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FIGURE 1. ADC1175-50 Timing Diagram



* Includes stray and distributed capacitance

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FIGURE 2. t_{EN} , t_{DIS} Test Circuit

Functional Description

The ADC1175-50 maintains superior dynamic performance with input frequencies up to 1/2 the clock frequency, achieving 6.8 effective bits with a 50 MHz sampling rate and 25 MHz input frequency.

The analog signal at V_{IN} that is within the voltage range set by V_{RT} and V_{RB} are digitized to eight bits at up to 55 MSPS. Input voltages below V_{RB} will cause the output word to consist of all zeroes. Input voltages above V_{RT} will cause the output word to consist of all ones. While the ADC1175-50 is specified for top and bottom reference voltages (V_{RT} and V_{RB}) or 2.6V and 0.6V, respectively, and will give best performance at these values, V_{RT} has a range of 1.0V to the analog supply voltage, AV_{DD} , while V_{RB} has a range of 0V to 4.0V. V_{RT} should always be at least 1.0V more positive than V_{RB} . With V_{RT} voltages above 2.8V, it is necessary to reduce the clock frequency to maintain SINAD performance. V_{RT} should always be between 1.0V and 2.8V more positive than V_{RB} .

If V_{RT} and V_{RTS} are connected together and V_{RB} and V_{RBS} are connected together, the nominal values of V_{RT} and V_{RB} are 2.6V and 0.6V, respectively. If V_{RT} and V_{RTS} are connected together and V_{RB} is grounded, the nominal value of V_{RT} is 2.3V.

Data is acquired at the falling edge of the clock and the digital equivalent of that data is available at the digital outputs 2.5 clock cycles plus t_{OD} later. The ADC1175-50 will convert as long as the clock signal is present at the CLK pin. The PD pin, when high, puts the device into the Power Down mode. When the PD pin is low, the device is in the normal operating mode.

The Power Down pin (PD), when high, puts the ADC1175-50 into a power down mode where power consumption is typi-

cally less than 5 mW. When the part is powered down, the digital output pins are in a high impedance TRI-STATE. It takes about 140 ns for the part to become active upon coming out of the power down mode.

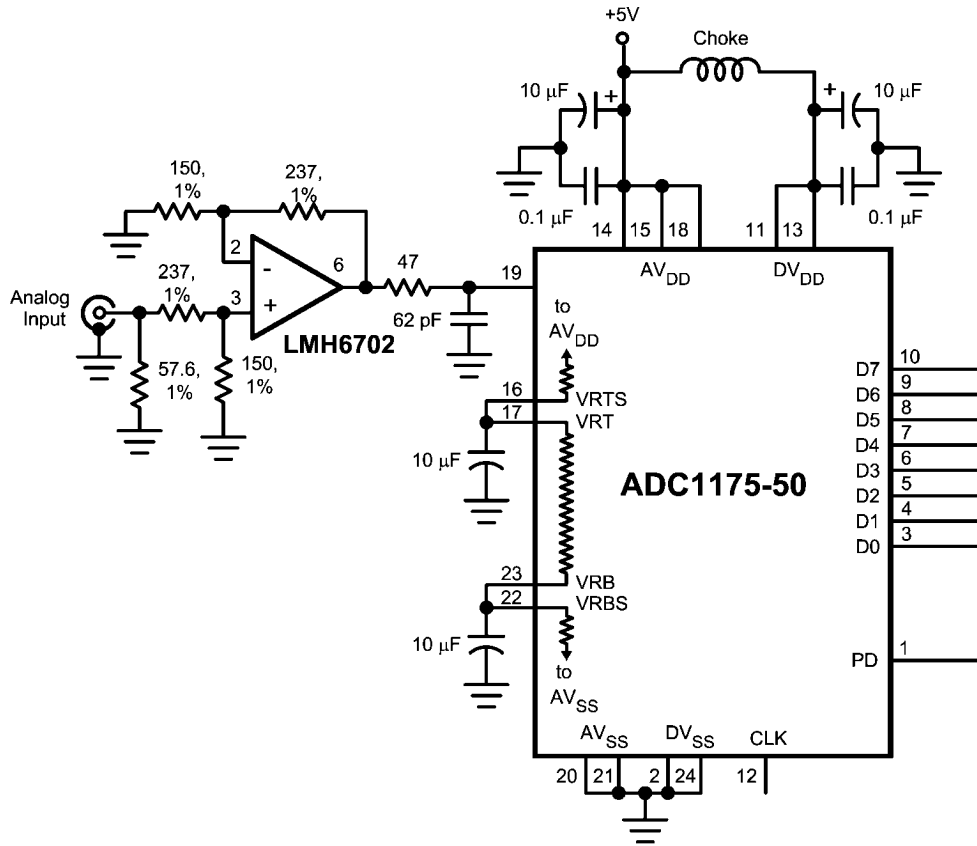
Applications Information

(All Schematic pin numbers refer to the TSSOP.)

1.0 THE ANALOG INPUT

The analog input of the ADC1175-50 is a switch followed by an integrator. That is, a switched capacitor input, appearing as 4 pF when the clock is low, and 7 pF when the clock is high. Switched capacitor inputs produce voltage spikes at the input pin at the ADC sample rate. There should be no attempt to eliminate these spikes, but they should settle out during the sample period (the clock high time). An RC at the ADC analog input pin, as shown in *Figure 3*, will help. For Nyquist applications, the capacitor should be about 10 times ADC track mode input capacitance and the pole frequency of this RC should be about the ADC sample rate. The LMH6702, and the LMH6609 have been found to be excellent amplifiers for driving the ADC1175-50. Do not drive the input beyond the supply rails. *Figure 3* shows an example of an input circuit using the LMH6702.

Driving the analog input with input signals up to $2.8 V_{P-P}$ will result in normal behavior where signals above V_{RT} will result in a code of FFh and input voltages below V_{RB} will result in an output code of zero. Input signals above $2.8 V_{P-P}$ may result in odd behavior where the output code is not FFh when the input exceeds V_{RT} .



10089625

FIGURE 3. Driving the ADC1175-50. Choose an op-amp that can drive a dynamic capacitance.

2.0 REFERENCE INPUTS

The reference inputs V_{RT} (Reference Top) and V_{RB} (Reference Bottom) are the top and bottom of the reference ladder. Input signals between these two voltages will be digitized to 8 bits. External voltages applied to the reference input pins should be within the range specified in the Operating Ratings table (1.0V to AV_{DD} for V_{RT} and 0V to ($AV_{DD} - 1.0V$) for V_{RB}). Any device used to drive the reference pins should be able to source sufficient current into the V_{RT} pin and sink sufficient current from the V_{RB} pin.

The reference ladder can be self-biased by connecting V_{RT} to V_{RTS} and connecting the V_{RB} to V_{RBS} to provide top and bottom reference voltages of approximately 2.6V and 0.6V, respectively, with $V_{CC} = 5.0V$. This connection is shown in Figure 3. If V_{RT} and V_{RTS} are tied together, but V_{RB} is tied to analog ground, a top reference voltage of approximately 2.3V is generated. The top and bottom of the ladder should be bypassed with 10 μF tantalum capacitors located close to the reference pins.

The reference self-bias circuit of Figure 3 is very simple and performance is adequate for many applications. Better linearity performance can generally be achieved by driving the reference pins with a low impedance source.

By forcing a little current into or out of the top and bottom of the ladder, as shown in Figure 4, the top and bottom reference voltages can be trimmed and performance improved over the self-bias method of Figure 3. The resistive divider at the amplifier inputs can be replaced with potentiometers, if desired. The LMC662 amplifier shown was chosen for its low offset voltage and low cost. Note that a negative power supply is

needed for these amplifiers if the lower one is required to go slightly negative to force the required reference voltage.

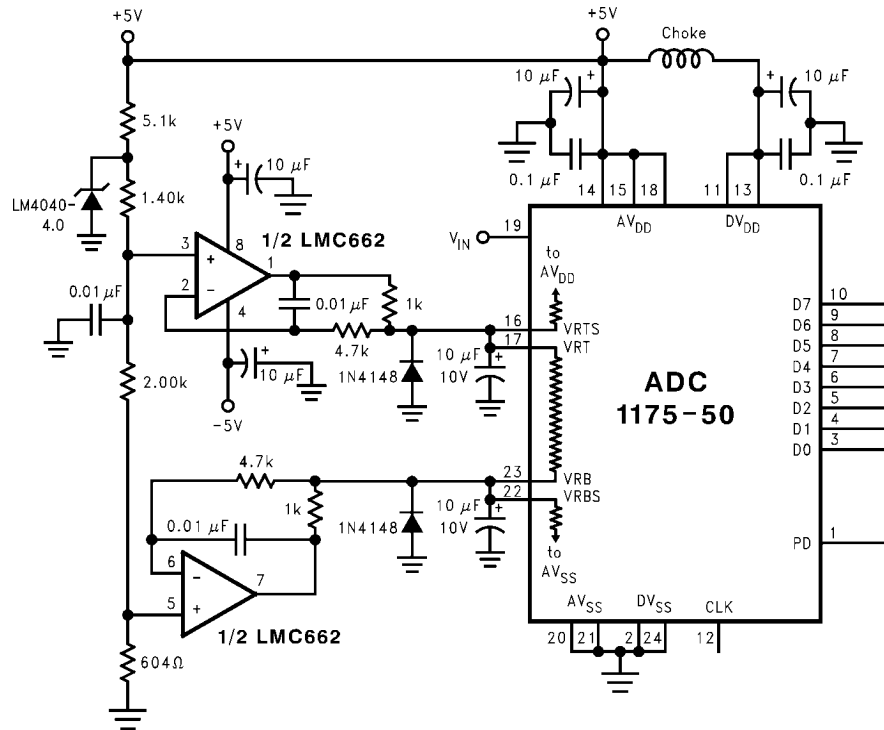
If reference voltages are desired that are more than a few tens of millivolts from the self-bias values, the circuit of Figure 5 will allow forcing the reference voltages to whatever levels are desired. This circuit provides the best performance because of the low source impedance of the transistors. Note that the V_{RTS} and V_{RBS} pins are left floating.

To minimize noise effects and ensure accurate conversions, the total reference voltage range ($V_{RT} - V_{RB}$) should be a minimum of 1.0V and a maximum of about 2.8V.

The ADC1175-50 is designed to operate with top and bottom references of 2.6V and 0.6V, respectively. However, it will function with reduced performance with a top reference voltage as high as AV_{DD} and a bottom reference voltage as low as ground.

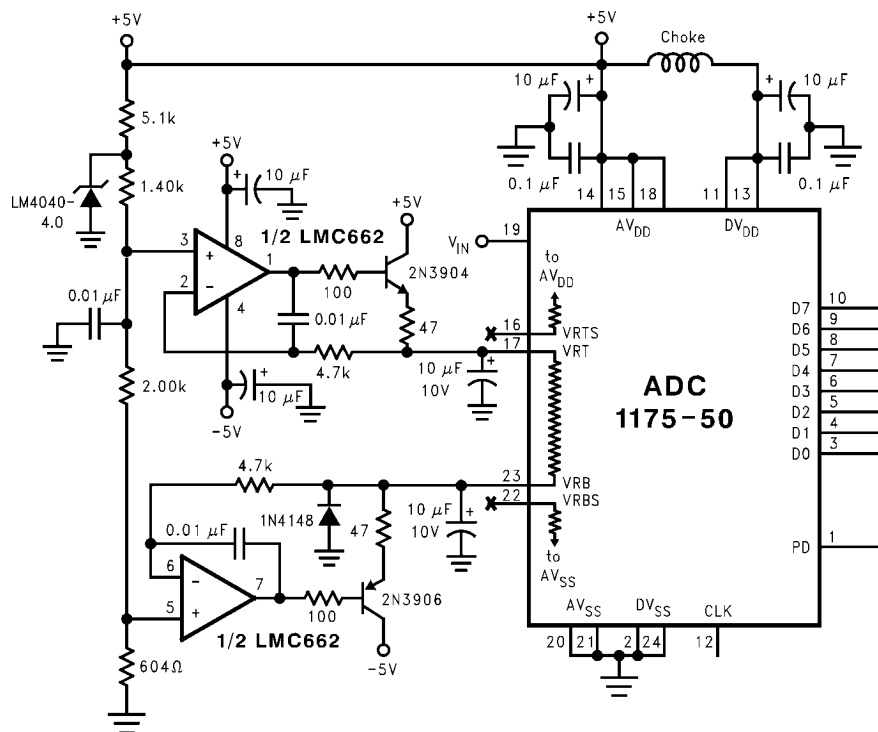
If reference voltages are desired that are more than a few tens of millivolts from the self-bias values, the circuit of Figure 5 will allow forcing the reference voltages to whatever levels are desired. This circuit provides the best performance because of the low source impedance of the transistors. Note that the V_{RTS} and V_{RBS} pins are left floating.

V_{RT} can be anywhere between $V_{RB} + 1.0V$ and the analog supply voltage, and V_{RB} can be anywhere between ground and 1.0V below V_{RT} . To minimize noise effects and ensure accurate conversions, the total reference voltage range ($V_{RT} - V_{RB}$) should be a minimum of 1.0V and a maximum of about 2.8V. If V_{RB} is not required to be below about +700mV, the -5V points in Figure 5 can be returned to ground and the negative supply eliminated.



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FIGURE 4. Better Defining the ADC Reference Voltage. Self bias is still used, but the reference voltages are trimmed by providing a small trim current with the operational amplifiers.



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FIGURE 5. Driving the Reference to Force Desired Values requires driving with a low impedance source, provided by the transistors. Note that pins 16 and 22 are not connected.

3.0 OUTPUT DATA TIMING

The Output Delay (t_{OD}) of the ADC1175-50 can be very close to one half clock cycle. Because of this, the output data transition occurs very near the falling edge of the ADC clock. To avoid clocking errors, you should use the *rising* edge of the ADC clock to latch the output data of the ADC1175-50 and *not* use the falling edge.

4.0 POWER SUPPLY CONSIDERATIONS

Many A/D converters draw sufficient transient current to corrupt their own power supplies if not adequately bypassed. A 10 μ F tantalum or aluminum electrolytic capacitor should be placed within an inch (2.5 centimeters) of the A/D power pins, with a 0.1 μ F ceramic chip capacitor placed as close as possible to the converter's power supply pins. Leadless chip capacitors are preferred because they have low lead inductance.

While a single voltage source should be used for the analog and digital supplies of the ADC1175-50, these supply pins should be isolated from each other to prevent any digital noise from being coupled to the analog power pins. We recommended a wide band choke, such as the JW Miller FB20010-3B, be used between the analog and digital supply lines, with a ceramic capacitor close to the analog supply pin. If a resistor is used in place of the choke, a maximum of 10 Ω should be used.

The converter digital supply should *not* be the supply that is used for other digital circuitry on the board. It should be the same supply used for the A/D analog supply.

As with all high speed converters, the ADC1175-50 should be assumed to have little a.c. power supply rejection, especially when self biasing is used by connecting V_{RT} and V_{RTS} together.

No pin should ever have a voltage on it that is in excess of the supply voltage or below ground, not even on a transient basis. This can be a problem upon application of power to a circuit. Be sure that the supplies to circuits driving the CLK, PD, analog input and reference pins do not come up any faster than does the voltage at the ADC1175-50 power pins.

Pins 11 and 13 are both labeled DV_{DD} . Pin 11 is the supply point for the digital core of the ADC, where pin 13 is used only to provide power to the ADC output drivers. As such, pin 11 may be connected to a voltage source that is less than the +5V used for AV_{DD} and DV_{DD} to ease interfacing to low voltage devices. Pin 11 should never exceed the pin 13 potential by more than 0.5V.

5.0 THE ADC1175-50 CLOCK

Although the ADC1175-50 is tested and its performance is guaranteed with a 50 MHz clock, it typically will function with clock frequencies from 1 MHz to 55 MHz.

The clock should be one of low jitter and close to 50% duty cycle.

6.0 LAYOUT AND GROUNDING

Proper grounding and proper routing of all signals is essential to ensure accurate conversion. Separate analog and digital ground planes that are connected beneath the ADC1175-50 may be used, but best EMI practices require a single ground plane. However, it is important to keep analog signal lines away from digital signal lines and away from power supply currents. This latter requirement requires the careful separation and placement of power planes. The use of power traces rather than one or more power planes is not recommended as higher frequencies are not well filtered with lumped capacitances. To filter higher frequency noise components it is

necessary to have sufficient capacitance between the power and ground planes.

If separate analog and digital ground planes are used, the analog and digital grounds may be in the same layer, but should be separated from each other. If separate analog and digital ground layers are used, they should *never overlap* each other.

Capacitive coupling between a typically noisy digital ground plane and the sensitive analog circuitry can lead to poor performance that may seem impossible to isolate and remedy. The solution is to keep the analog circuitry well separated from the digital circuitry.

Digital circuits create substantial supply and ground current transients. The logic noise thus generated could have significant impact upon system noise performance. The best logic family to use in systems with A/D converters is one which employs non-saturating transistor designs, or has low noise characteristics, such as the 74LS and the 74HC(T) families. The worst noise generators are logic families that draw the largest supply current transients during clock or signal edges, like the 74F family. In general, slower logic families will produce less high frequency noise than do high speed logic families.

Since digital switching transients are composed largely of high frequency components, total ground plane copper weight will have little effect upon the logic-generated noise. This is because of the skin effect. Total surface area is more important than is total ground plane volume.

An effective way to control ground noise is by using a single, solid ground plane and splitting the power plane into analog and digital areas and to have power and ground planes in adjacent board layers. There should be no traces within either the power or the ground layers of the board. The analog and digital power planes should reside in the same board layer so that they can not overlap each other. The analog and digital power planes define the analog and digital areas of the board.

Mount digital components and run digital lines only in the digital areas of the board. Mount the analog components and run analog lines only in the analog areas of the board. Be sure to treat all digital lines greater than one inch for each nanosecond of rise time as transmission lines. That is, they should be of constant, controlled impedance, be properly terminated at the source end and run from one point to another single point.

The back of the LLP package has a large metal area inside the area bounded by the pins. This metal area is connected to the die substrate (ground). This pad may be left floating if desired. If it is connected to anything, it should be to ground near the connection between analog and digital ground planes. Soldering this metal pad to ground will help keep the die cooler and could yield improved performance because of the lower impedance between die and board grounds. However, a poor layout could compromise performance.

Generally, analog and digital lines should cross each other at 90° to avoid getting digital noise into the analog path. In high frequency systems, however, avoid crossing analog and digital lines altogether. Clock lines should be isolated from ALL other lines, analog AND digital. Even the generally accepted 90° crossing should be avoided as even a little coupling can cause problems at high frequencies. Best performance at high frequencies and at high resolution is obtained with a straight signal path.

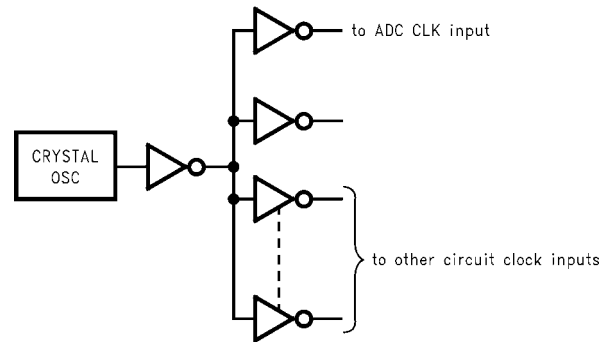
Be especially careful with the layout of inductors. Mutual inductance can change the characteristics of the circuit in which they are used. Inductors should not be placed side by side

with each other, not even with just a small part of their bodies beside each other.

The analog input should be isolated from noisy signal traces to avoid coupling of spurious signals into the input. Any external component (e.g., a filter capacitor) connected between the converter's input and ground should be connected to a very clean point in the ground plane.

7.0 DYNAMIC PERFORMANCE

The ADC1175-50 is a.c. tested and its dynamic performance is guaranteed. To meet the published specifications, the clock source driving the CLK input must be free of jitter. For best a.c. performance, isolating the ADC clock from any digital circuitry should be done with adequate buffers, as with a clock tree. See *Figure 6*.



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FIGURE 6. Isolating the ADC Clock from Digital Circuitry

It is good practice to keep the ADC clock line as short as possible and to keep it well away from any other signals. Other signals can introduce jitter into the clock signal.

8.0 COMMON APPLICATION PITFALLS

Driving the inputs (analog or digital) beyond the power supply rails. For proper operation, all inputs should not go more than 50 mV below the ground pins or 50 mV above the supply pins. Exceeding these limits on even a transient basis may cause faulty or erratic operation. It is not uncommon for high speed digital circuits to exhibit undershoot that goes more than a volt below ground due to improper termination. A resistor of about 50Ω to 100Ω in series with the offending digital input, located close to the signal source, will usually eliminate the problem.

Care should be taken not to overdrive the inputs of the ADC1175-50. Such practice may lead to conversion inaccuracies and even to device damage.

Attempting to drive a high capacitance digital data bus. The more capacitance the output drivers have to charge for each conversion, the more instantaneous digital current is required from DV_{DD} and DGND. These large charging current spikes can couple into the analog section, degrading dynamic performance. Buffering the digital data outputs (with a 74AC541, for example) may be necessary if the data bus to be driven is heavily loaded. Dynamic performance can also be improved by adding 47Ω series resistors at each digital output, reducing the energy coupled back into the converter output pins.

Using an inadequate amplifier to drive the analog input. As explained in Section 1.0, the ADC input is a switched capacitor one and there are voltage spikes present there. This type of input is more difficult to drive than is a fixed capacitance, and should be considered when choosing a driving

device. The LMH6702 and the LMH6609 have been found to be an excellent device for driving the ADC1175-50. Also remember to use the RC between the driving source and the ADC input, as explained in Section 1.0.

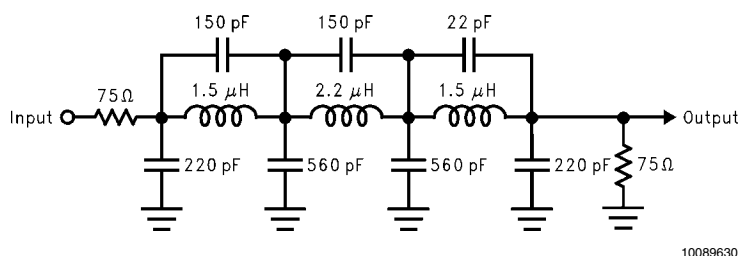
Driving the V_{RT} pin or the V_{RB} pin with devices that can not source or sink the current required by the ladder. As mentioned in Section 2.0, care should be taken to see that any driving devices can source sufficient current into the V_{RT} pin and sink sufficient current from the V_{RB} pin. If these pins are not driven with devices that can handle the required current, these reference pins will not be stable, resulting in a reduction of dynamic performance.

Using a clock source with excessive jitter, using excessively long clock signal trace, or having other signals coupled to the clock signal trace. This will cause the sampling interval to vary, causing excessive output noise and a reduction in SNR performance. Simple gates with RC timing is generally inadequate as a clock source.

Input test signal contains harmonic distortion that interferes with the measurement of dynamic signal to noise ratio. Harmonic and other interfering signals can be removed by inserting a filter at the signal input. Suitable filters are

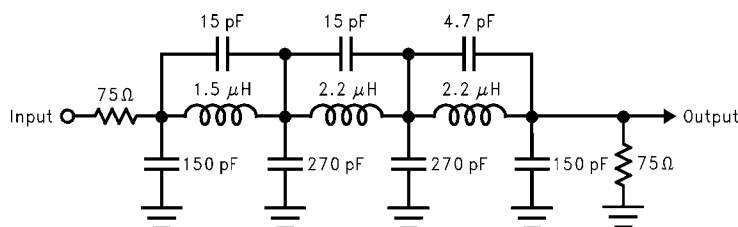
shown in *Figure 7* and *Figure 8*. The circuit of *Figure 7* has a cutoff of about 5.5 MHz and is suitable for input frequencies of 1 MHz to 5 MHz. The circuit of *Figure 8* has a cutoff of about 11 MHz and is suitable for input frequencies of 5 MHz to 10 MHz. These filters should be driven by a generator of 75 Ω source impedance and terminated with a 75 Ω resistor.

Not considering the effect on a driven CMOS digital circuit(s) when the ADC1175-50 is in the power down mode. Because the ADC1175-50 output goes into a high impedance state when in the power down mode, any CMOS device connected to these outputs will have their inputs floating when the ADC is in power down. Should the inputs of the circuit being driven by the ADC digital outputs float to a level near 2.5V, a CMOS device could exhibit relative large supply currents as the input stage toggles rapidly. The solution is to use pull-down resistors at the ADC outputs. The value of these resistors is not critical, as long as they do not cause excessive currents in the outputs of the ADC1175-50. Low pull-down resistor values could result in degraded SNR and SINAD performance of the ADC1175-50. Values between 5 k Ω and 10 k Ω should work well.



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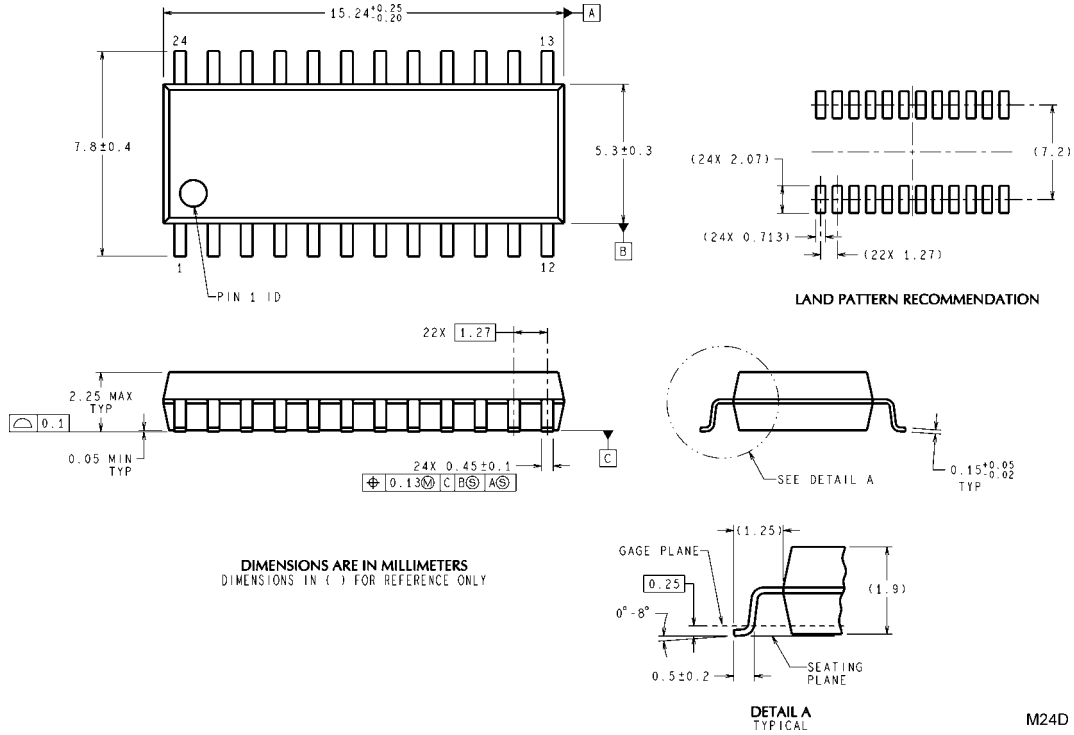
FIGURE 7. A 5.5 MHz Low Pass filter to eliminate harmonics at the signal input. Use with maximum input frequencies of 1 MHz to 5 MHz.



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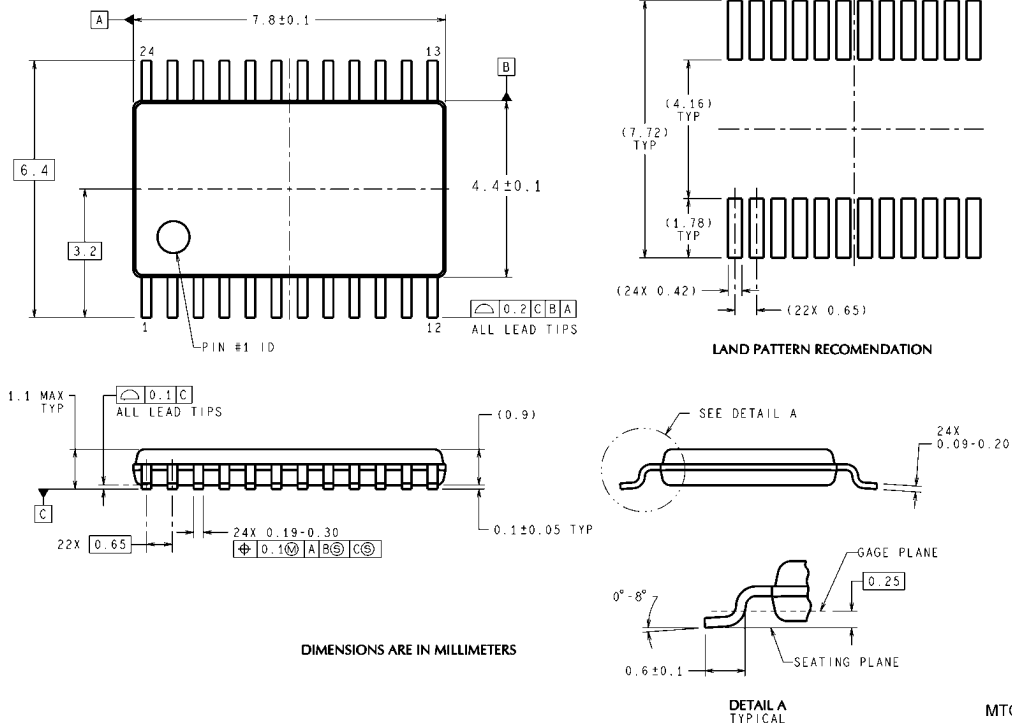
FIGURE 8. An 11 MHz Low Pass filter to eliminate harmonics at the signal input. Use with maximum input frequencies of 5 MHz to 10 MHz

Physical Dimensions inches (millimeters) unless otherwise noted



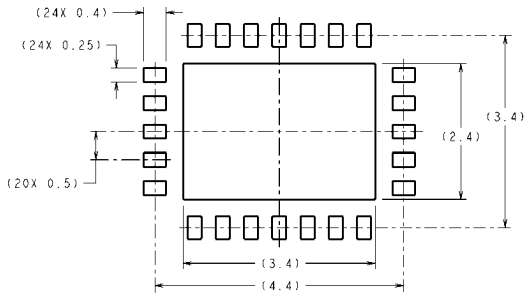
M24D (Rev B)

24-Lead Package JM
Order Number ADC1175-50CIJM
Product in the SOIC (EIAJ) package is obsolete. Shown for reference only.
NS Package Number M24D

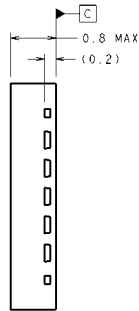
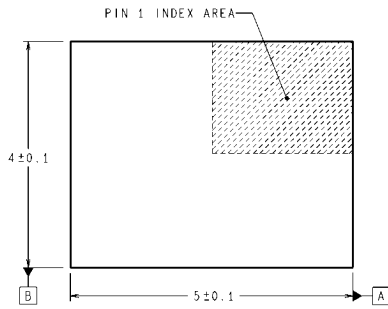


MTC24 (Rev E)

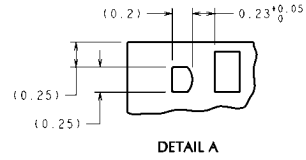
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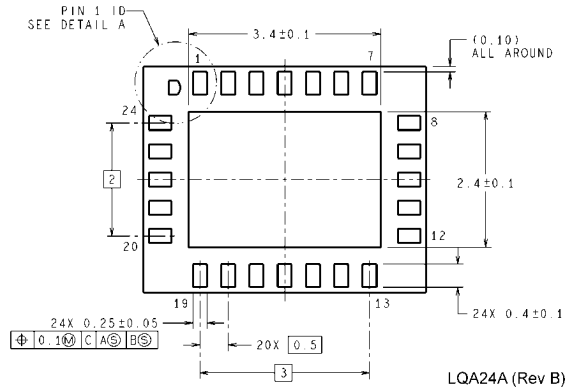
RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



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DETAIL A



LQA24A (Rev B)

24-Lead Package LLP
Order Number ADC1175-50C1LQX
NS Package Number LQA24A

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